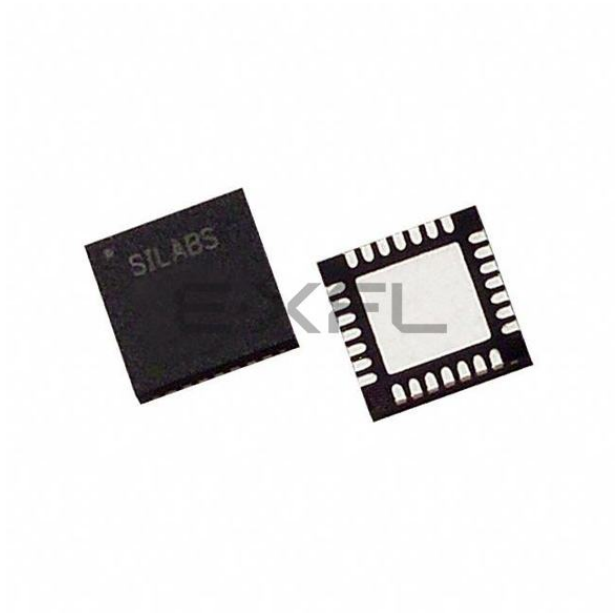

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	25MHz
Connectivity	SMBus (2-Wire/I²C), SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	25
Program Memory Size	8KB (8K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	1.25K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VFQFN Exposed Pad
Supplier Device Package	28-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051t615-gmr

5. QFN-28 Package Specifications

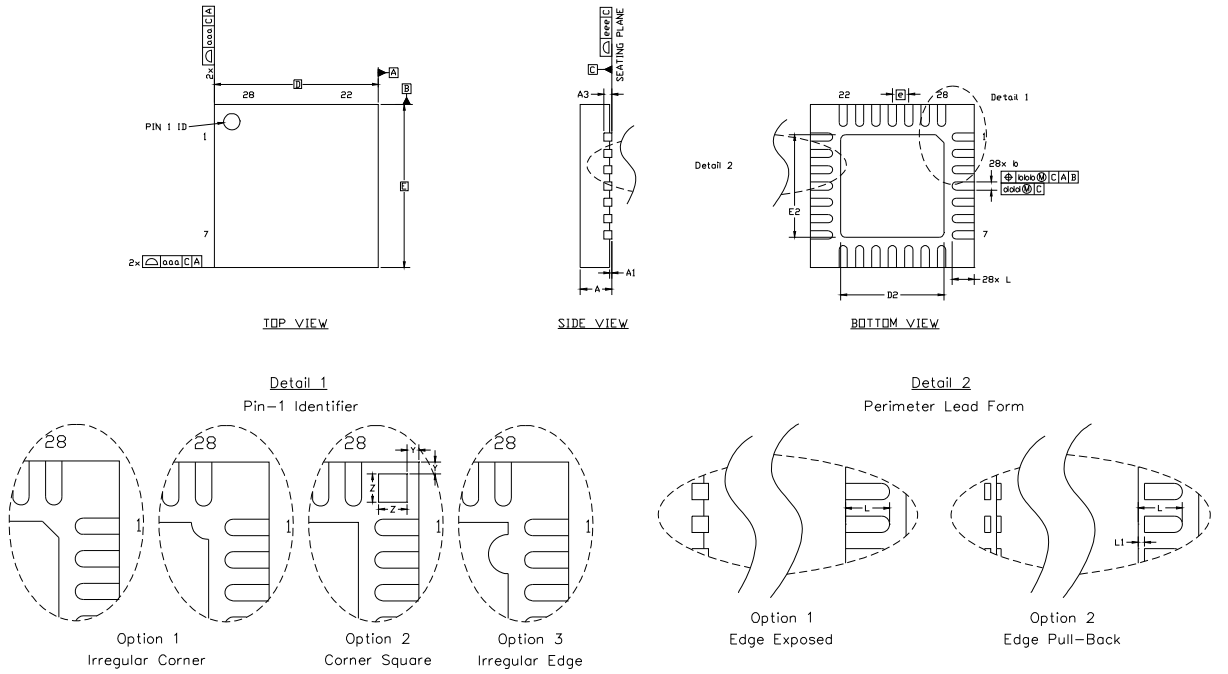


Figure 5.1. QFN-28 Package Drawing

Table 5.1. QFN-28 Package Dimensions

Dimension	Min	Typ	Max
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3		0.25 REF	
b	0.18	0.23	0.30
D		5.00 BSC.	
D2	2.90	3.15	3.35
e		0.50 BSC.	
E		5.00 BSC.	
E2	2.90	3.15	3.35

Dimension	Min	Typ	Max
L	0.35	0.55	0.65
L1	0.00	—	0.15
aaa		0.15	
bbb		0.10	
ddd		0.05	
eee		0.08	
Z		0.44	
Y		0.18	

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. This drawing conforms to the JEDEC Solid State Outline MO-220, variation VHHD except for custom features D2, E2, Z, Y, and L which are toleranced per supplier designation.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

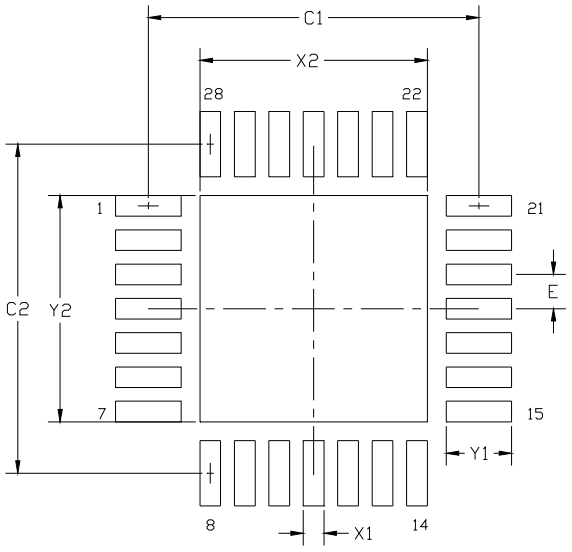


Figure 5.2. QFN-28 Recommended PCB Land Pattern

Table 5.2. QFN-28 PCB Land Pattern Dimesions

Dimension	Min	Max
C1	4.80	
C2	4.80	
E	0.50	
X1	0.20	0.30

Dimension	Min	Max
X2	3.20	3.30
Y1	0.85	0.95
Y2	3.20	3.30

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.

Solder Mask Design

4. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60µm minimum, all the way around the pad.

Stencil Design

5. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
6. The stencil thickness should be 0.125mm (5 mils).
7. The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pins.
8. A 3x3 array of 0.90mm openings on a 1.1mm pitch should be used for the center pad to assure the proper paste volume.

Card Assembly

9. A No-Clean, Type-3 solder paste is recommended.
10. The recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

7. Electrical Characteristics

7.1. Absolute Maximum Specifications

Table 7.1. Absolute Maximum Ratings

Parameter	Conditions	Min	Typ	Max	Units
Ambient temperature under bias		–55	—	125	°C
Storage Temperature		–65	—	150	°C
Voltage on $\overline{RST}$ or any Port I/O Pin (except V_{PP} during programming) with respect to GND	$V_{DD} \geq 2.2$ V $V_{DD} < 2.2$ V	–0.3 –0.3	— —	5.8 V_{DD} + 3.6	V V
Voltage on V_{PP} with respect to GND during a programming operation	$V_{DD} > 2.4$ V	–0.3	—	7.0	V
Duration of High-voltage on V_{PP} pin (cumulative)	$V_{PP} > (V_{DD} + 3.6$ V)	—	—	10	s
Voltage on V_{DD} with respect to GND	Regulator in Normal Mode Regulator in Bypass Mode	–0.3 –0.3	— —	4.2 1.98	V V
Maximum Total current through V_{DD} and GND		—	—	500	mA
Maximum output current sunk by $\overline{RST}$ or any Port pin		—	—	100	mA

Note: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Table 7.9. Temperature Sensor Electrical Characteristics

V_{DD} = 3.0 V, –40 to +85 °C unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
Linearity		—	±0.5	—	°C
Slope		—	3.49	—	mV/°C
Slope Error*		—	±40	—	µV/°C
Offset	Temp = 0 °C	—	930	—	mV
Offset Error*	Temp = 0 °C	—	±12	—	mV
Note: Represents one standard deviation from the mean.					

Table 7.10. Voltage Reference Electrical Characteristics

V_{DD} = 3.0 V; –40 to +85 °C unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
Input Voltage Range		0	—	V_{DD}	V
Input Current	Sample Rate = 500 ksps; VREF = 2.5 V	—	12	—	µA

8.3.3. Settling Time Requirements

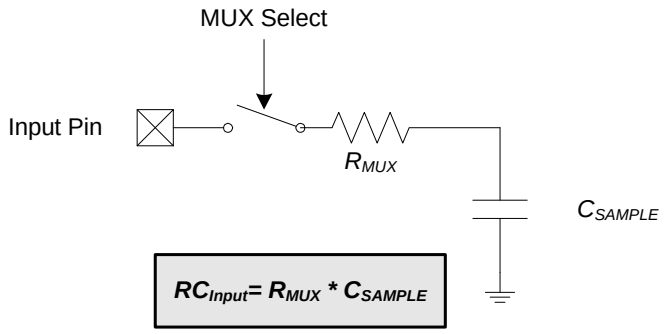
A minimum tracking time is required before each conversion to ensure that an accurate conversion is performed. This tracking time is determined by any series impedance, including the AMUX0 resistance, the the ADC0 sampling capacitance, and the accuracy required for the conversion. Note that in delayed tracking mode, three SAR clocks are used for tracking at the start of every conversion. For many applications, these three SAR clocks will meet the minimum tracking time requirements.

Figure 8.3 shows the equivalent ADC0 input circuit. The required ADC0 settling time for a given settling accuracy (SA) may be approximated by Equation 8.1. See Table 7.8 for ADC0 minimum settling time requirements as well as the mux impedance and sampling capacitor values.

$$t = \ln\left(\frac{2^n}{SA}\right) \times R_{TOTAL} C_{SAMPLE}$$

Equation 8.1. ADC0 Settling Time Requirements

Where:
SA is the settling accuracy, given as a fraction of an LSB (for example, 0.25 to settle within 1/4 LSB)
t is the required settling time in seconds
R_{TOTAL} is the sum of the AMUX0 resistance and any external source resistance.
n is the ADC resolution in bits (10).



Note: See electrical specification tables for R_{MUX} and C_{SAMPLE} parameters.

Figure 8.3. ADC0 Equivalent Input Circuits

SFR Definition 8.1. ADC0CF: ADC0 Configuration

Bit	7	6	5	4	3	2	1	0
Name	AD0SC[4:0]					AD0LJST	AD08BE	AMP0GN0
Type	R/W					R/W	R/W	R/W
Reset	1	1	1	1	1	0	0	1

SFR Address = 0xBC

Bit	Name	Function
7:3	AD0SC[4:0]	**ADC0 SAR Conversion Clock Period Bits.** SAR Conversion clock is derived from system clock by the following equation, where *AD0SC* refers to the 5-bit value held in bits AD0SC4–0. SAR Conversion clock requirements are given in the ADC specification table. $AD0SC = \frac{SYSCLK}{CLK_{SAR}} - 1$ **Note:** If the Memory Power Controller is enabled (MPCE = '1'), AD0SC must be set to at least "00001" for proper ADC operation.
2	AD0LJST	**ADC0 Left Justify Select.** 0: Data in ADC0H:ADC0L registers are right-justified. 1: Data in ADC0H:ADC0L registers are left-justified. **Note:** The AD0LJST bit is only valid for 10-bit mode (AD08BE = 0).
1	AD08BE	**8-Bit Mode Enable.** 0: ADC operates in 10-bit mode (normal). 1: ADC operates in 8-bit mode. **Note:** When AD08BE is set to 1, the AD0LJST bit is ignored.
0	AMP0GN0	**ADC Gain Control Bit.** 0: Gain = 0.5 1: Gain = 1

SFR Definition 8.9. AMX0P: AMUX0 Positive Channel Select

Bit	7	6	5	4	3	2	1	0
Name				AMX0P[4:0]				
Type	R	R	R	R/W				
Reset	0	0	0	1	1	1	1	1

SFR Address = 0xBB

Bit	Name	Function		
7:5	Unused	Unused. Read = 000b; Write = Don't Care.		
4:0	AMX0P[4:0]	**AMUX0 Positive Input Selection.**		
		Setting	Channel	Available on Packages
		00000:	P1.0	LQFP-32, QFN-28, QFN-24
		00001:	P1.1	LQFP-32, QFN-28, QFN-24
		00010:	P1.2	LQFP-32, QFN-28, QFN-24
		00011:	P1.3	LQFP-32, QFN-28, QFN-24
		00100:	P1.4	LQFP-32, QFN-28, QFN-24
		00101:	P1.5	LQFP-32, QFN-28, QFN-24
		00110:	P1.6	LQFP-32, QFN-28
		00111:	P1.7	LQFP-32, QFN-28
		01000:	P2.0	LQFP-32, QFN-28, QFN-24
		01001:	P2.1	LQFP-32, QFN-28, QFN-24
		01010:	P2.2	LQFP-32, QFN-28, QFN-24
		01011:	P2.3	LQFP-32, QFN-28, QFN-24
		01100:	P2.4	LQFP-32, QFN-28, QFN-24
		01101:	P2.5	LQFP-32, QFN-28, QFN-24
		01110:	P2.6	LQFP-32, QFN-28
		01111:	P2.7	LQFP-32, QFN-28
		10000:	P3.0	LQFP-32, QFN-28, QFN-24
		10001:	P3.1	LQFP-32
		10010:	P3.2	LQFP-32
		10011:	P3.3	LQFP-32
		10100:	P3.4	LQFP-32
		10101-11101:	No Input Selected	N/A
		11110:	Temp Sensor	LQFP-32, QFN-28, QFN-24
		11111:	V_{DD}	LQFP-32, QFN-28, QFN-24

11. Voltage Regulator (REG0)

C8051T610/1/2/3/4/5/6/7 devices include an internal voltage regulator (REG0) to regulate the internal core supply to 1.8 V from a V_{DD} supply of 1.8 to 3.6 V. Two power-saving modes are built into the regulator to help reduce current consumption in low-power applications. These modes are accessed through the REG0CN register (SFR Definition 11.1). Electrical characteristics for the on-chip regulator are specified in Table 7.5 on page 34

If an external regulator is used to power the device, the internal regulator may be put into bypass mode using the BYPASS bit. **The internal regulator should never be placed in bypass mode unless an external 1.8 V regulator is used to supply V_{DD}. Doing so could cause permanent damage to the device.**

Under default conditions, when the device enters STOP mode the internal regulator will remain on. This allows any enabled reset source to generate a reset for the device and bring the device out of STOP mode. For additional power savings, the STOPCF bit can be used to shut down the regulator and the internal power network of the device when the part enters STOP mode. When STOPCF is set to 1, the $\overline{\text{RST}}$ pin or a full power cycle of the device are the only methods of generating a reset.

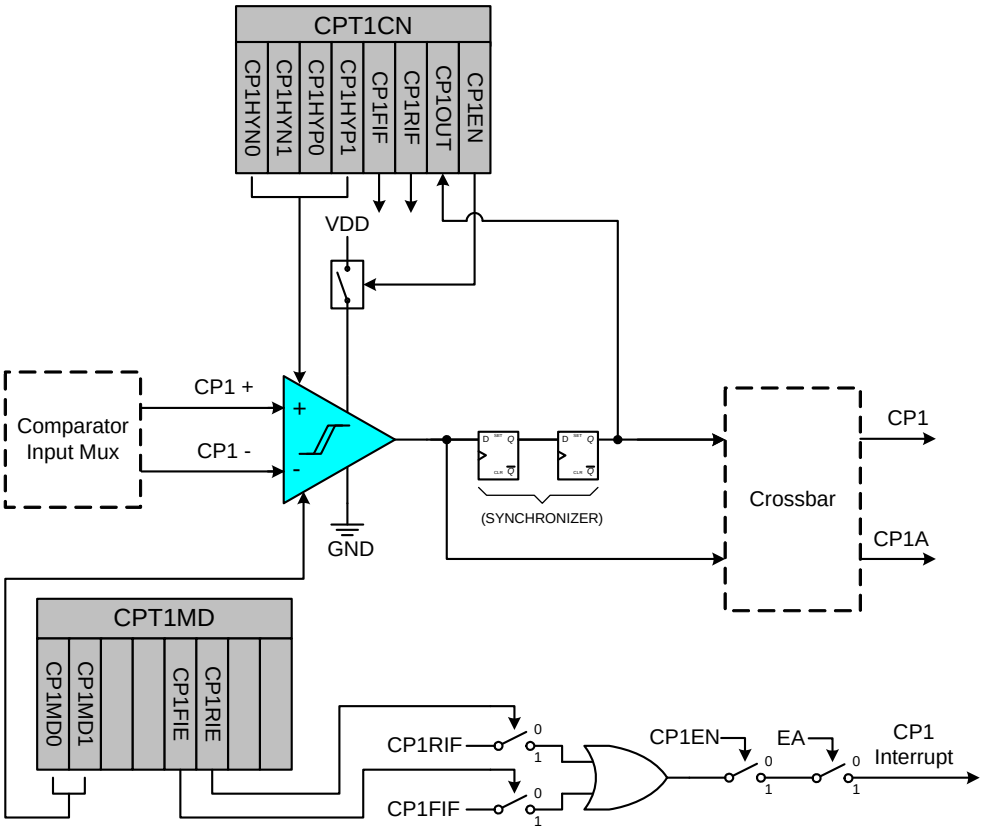


Figure 12.2. Comparator1 Functional Block Diagram

The Comparator output can be polled in software, used as an interrupt source, and/or routed to a Port pin. When routed to a Port pin, the Comparator output is available asynchronous or synchronous to the system clock; the asynchronous output is available even in STOP mode (with no system clock active). When disabled, the Comparator output (if assigned to a Port I/O pin via the Crossbar) defaults to the logic low state, and the power supply to the comparator is turned off. See Section “21.3. Priority Crossbar Decoder” on page 117 for details on configuring Comparator outputs via the digital Crossbar. Comparator inputs can be externally driven from –0.25 V to (V_{DD}) + 0.25 V without damage or upset. The complete Comparator electrical specifications are given in Section “7. Electrical Characteristics” on page 31.

The Comparator response time may be configured in software via the CPTnMD registers (see SFR Definition 12.2 and SFR Definition 12.4). Selecting a longer response time reduces the Comparator supply current.

SFR Definition 12.1. CPT0CN: Comparator0 Control

Bit	7	6	5	4	3	2	1	0
Name	CP0EN	CP0OUT	CP0RIF	CP0FIF	CP0HYP[1:0]		CP0HYN[1:0]	
Type	R/W	R	R/W	R/W	R/W		R/W	
Reset	0	0	0	0	0	0	0	0

SFR Address = 0x9B

Bit	Name	Function
7	CP0EN	**Comparator0 Enable Bit.** 0: Comparator0 Disabled. 1: Comparator0 Enabled.
6	CP0OUT	**Comparator0 Output State Flag.** 0: Voltage on CP0+ < CP0–. 1: Voltage on CP0+ > CP0–.
5	CP0RIF	**Comparator0 Rising-Edge Flag. Must be cleared by software.** 0: No Comparator0 Rising Edge has occurred since this flag was last cleared. 1: Comparator0 Rising Edge has occurred.
4	CP0FIF	**Comparator0 Falling-Edge Flag. Must be cleared by software.** 0: No Comparator0 Falling-Edge has occurred since this flag was last cleared. 1: Comparator0 Falling-Edge has occurred.
3:2	CP0HYP[1:0]	**Comparator0 Positive Hysteresis Control Bits.** 00: Positive Hysteresis Disabled. 01: Positive Hysteresis = 5 mV. 10: Positive Hysteresis = 10 mV. 11: Positive Hysteresis = 20 mV.
1:0	CP0HYN[1:0]	**Comparator0 Negative Hysteresis Control Bits.** 00: Negative Hysteresis Disabled. 01: Negative Hysteresis = 5 mV. 10: Negative Hysteresis = 10 mV. 11: Negative Hysteresis = 20 mV.

SFR Definition 12.2. CPT0MD: Comparator0 Mode Selection

Bit	7	6	5	4	3	2	1	0
Name			CP0RIE	CP0FIE			CP0MD[1:0]	
Type	R	R	R/W	R/W	R	R	R/W	
Reset	0	0	0	0	0	0	1	0

SFR Address = 0x9D

Bit	Name	Function
7:6	Unused	Unused. Read = 00b, Write = Don't Care.
5	CP0RIE	**Comparator0 Rising-Edge Interrupt Enable.** 0: Comparator0 Rising-edge interrupt disabled. 1: Comparator0 Rising-edge interrupt enabled.
4	CP0FIE	**Comparator0 Falling-Edge Interrupt Enable.** 0: Comparator0 Falling-edge interrupt disabled. 1: Comparator0 Falling-edge interrupt enabled.
3:2	Unused	Unused. Read = 00b, Write = don't care.
1:0	CP0MD[1:0]	**Comparator0 Mode Select.** These bits affect the response time and power consumption for Comparator0. 00: Mode 0 (Fastest Response Time, Highest Power Consumption) 01: Mode 1 10: Mode 2 11: Mode 3 (Slowest Response Time, Lowest Power Consumption)

14.2.1.1. General Purpose Registers

The lower 32 bytes of data memory, locations 0x00 through 0x1F, may be addressed as four banks of general-purpose registers. Each bank consists of eight byte-wide registers designated R0 through R7. Only one of these banks may be enabled at a time. Two bits in the program status word, RS0 (PSW.3) and RS1 (PSW.4), select the active register bank (see description of the PSW in SFR Definition 13.6). This allows fast context switching when entering subroutines and interrupt service routines. Indirect addressing modes use registers R0 and R1 as index registers.

14.2.1.2. Bit Addressable Locations

In addition to direct access to data memory organized as bytes, the sixteen data memory locations at 0x20 through 0x2F are also accessible as 128 individually addressable bits. Each bit has a bit address from 0x00 to 0x7F. Bit 0 of the byte at 0x20 has bit address 0x00 while bit7 of the byte at 0x20 has bit address 0x07. Bit 7 of the byte at 0x2F has bit address 0x7F. A bit access is distinguished from a full byte access by the type of instruction used (bit source or destination operands as opposed to a byte source or destination).

The MCS-51™ assembly language allows an alternate notation for bit addressing of the form XX.B where XX is the byte address and B is the bit position within the byte. For example, the instruction:

```
MOV    C, 22.3h
```

moves the Boolean value at 0x13 (bit 3 of the byte at location 0x22) into the Carry flag.

14.2.1.3. Stack

A programmer's stack can be located anywhere in the 256-byte data memory. The stack area is designated using the Stack Pointer (SP) SFR. The SP will point to the last location used. The next value pushed on the stack is placed at SP+1 and then SP is incremented. A reset initializes the stack pointer to location 0x07. Therefore, the first value pushed on the stack is placed at location 0x08, which is also the first register (R0) of register bank 1. Thus, if more than one register bank is to be used, the SP should be initialized to a location in the data memory not being used for data storage. The stack depth can extend up to 256 bytes.

14.2.2. External RAM

There are 1024 bytes of on-chip RAM mapped into the external data memory space. All of these address locations may be accessed using the external move instruction (MOVX) and the data pointer (DPTR), or using MOVX indirect addressing mode. If the MOVX instruction is used with an 8-bit address operand (such as @R1), then the high byte of the 16-bit address is provided by the External Memory Interface Control Register (EMI0CN as shown in SFR Definition 14.1).

For a 16-bit MOVX operation (@DPTR), the upper 7 bits of the 16-bit external data memory address word are "don't cares". As a result, the 1024-byte RAM is mapped modulo style over the entire 64 k external data memory address range. For example, the XRAM byte at address 0x0000 is shadowed at addresses 0x0400, 0x0800, 0x0C00, 0x1000, etc. This is a useful feature when performing a linear memory fill, as the address pointer doesn't have to be reset when reaching the RAM block boundary.

SFR Definition 16.3. EIE1: Extended Interrupt Enable 1

Bit	7	6	5	4	3	2	1	0
Name	ET3	ECP1	ECP0	EPCA0	EADC0	EWADC0	Reserved	ESMB0
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xE6

Bit	Name	Function
7	ET3	**Enable Timer 3 Interrupt.** This bit sets the masking of the Timer 3 interrupt. 0: Disable Timer 3 interrupts. 1: Enable interrupt requests generated by the TF3L or TF3H flags.
6	ECP1	**Enable Comparator1 (CP1) Interrupt.** This bit sets the masking of the CP1 interrupt. 0: Disable CP1 interrupts. 1: Enable interrupt requests generated by the CP1RIF or CP1FIF flags.
5	ECP0	**Enable Comparator0 (CP0) Interrupt.** This bit sets the masking of the CP0 interrupt. 0: Disable CP0 interrupts. 1: Enable interrupt requests generated by the CP0RIF or CP0FIF flags.
4	EPCA0	**Enable Programmable Counter Array (PCA0) Interrupt.** This bit sets the masking of the PCA0 interrupts. 0: Disable all PCA0 interrupts. 1: Enable interrupt requests generated by PCA0.
3	EADC0	**Enable ADC0 Conversion Complete Interrupt.** This bit sets the masking of the ADC0 Conversion Complete interrupt. 0: Disable ADC0 Conversion Complete interrupt. 1: Enable interrupt requests generated by the AD0INT flag.
2	EWADC0	**Enable Window Comparison ADC0 Interrupt.** This bit sets the masking of ADC0 Window Comparison interrupt. 0: Disable ADC0 Window Comparison interrupt. 1: Enable interrupt requests generated by ADC0 Window Compare flag (AD0WINT).
1	Reserved	Reserved. Must Write 0.
0	ESMB0	**Enable SMBus (SMB0) Interrupt.** This bit sets the masking of the SMB0 interrupt. 0: Disable all SMB0 interrupts. 1: Enable interrupt requests generated by SMB0.

19.5. Comparator0 Reset

Comparator0 can be configured as a reset source by writing a 1 to the C0RSEF flag (RSTSRC.5). Comparator0 should be enabled and allowed to settle prior to writing to C0RSEF to prevent any turn-on chatter on the output from generating an unwanted reset. The Comparator0 reset is active-low: if the non-inverting input voltage (on CP0+) is less than the inverting input voltage (on CP0-), the device is put into the reset state. After a Comparator0 reset, the C0RSEF flag (RSTSRC.5) will read 1 signifying Comparator0 as the reset source; otherwise, this bit reads 0. The state of the RST pin is unaffected by this reset.

19.6. PCA Watchdog Timer Reset

The programmable watchdog timer (WDT) function of the programmable counter array (PCA) can be used to prevent software from running out of control during a system malfunction. The PCA WDT function can be enabled or disabled by software as described in Section “26.4. Watchdog Timer Mode” on page 200; the WDT is enabled and clocked by SYSCLK/12 following any reset. If a system malfunction prevents user software from updating the WDT, a reset is generated and the WDTRSF bit (RSTSRC.5) is set to 1. The state of the RST pin is unaffected by this reset.

19.7. EPROM Error Reset

If an EPROM read or write targets an illegal address, a system reset is generated. This may occur due to any of the following:

- Programming hardware attempts to write or read an EPROM location which is above the user code space address limit.
- An EPROM read from firmware is attempted above user code space. This occurs when a MOVC operation is attempted above the user code space address limit.
- A Program read is attempted above user code space. This occurs when user code attempts to branch to an address above the user code space address limit.

The MEMERR bit (RSTSRC.6) is set following an EPROM error reset. The state of the RST pin is unaffected by this reset.

19.8. Software Reset

Software may force a reset by writing a 1 to the SWRSF bit (RSTSRC.4). The SWRSF bit will read 1 following a software forced reset. The state of the RST pin is unaffected by this reset.

20.2. Programmable Internal High-Frequency (H-F) Oscillator

All C8051T610/1/2/3/4/5/6/7 devices include a programmable internal high-frequency oscillator that defaults as the system clock after a system reset. The internal oscillator period can be adjusted via the OSCICL register as defined by SFR Definition 20.2.

On C8051T610/1/2/3/4/5/6/7 devices, OSCICL is factory calibrated to obtain a 24.5 MHz base frequency.

The system clock may be derived from the programmed internal oscillator divided by 1, 2, 4, or 8, as defined by the IFCN bits in register OSCICN. The divide value defaults to 8 following a reset.

SFR Definition 20.2. OSCICL: Internal H-F Oscillator Calibration

Bit	7	6	5	4	3	2	1	0
Name		OSCICL[6:0]						
Type	R	R/W						
Reset	0	Varies	Varies	Varies	Varies	Varies	Varies	Varies

SFR Address = 0xB3

Bit	Name	Function
7	Unused	Unused. Read = 0; Write = Don't Care
6:0	OSCICL[6:0]	**Internal Oscillator Calibration Bits.** These bits determine the internal oscillator period. When set to 0000000b, the H-F oscillator operates at its fastest setting. When set to 1111111b, the H-F oscillator operates at its slowest setting. The reset value is factory calibrated to generate an internal oscillator frequency of 24.5 MHz.

SFR Definition 21.2. XBR1: Port I/O Crossbar Register 1

Bit	7	6	5	4	3	2	1	0
Name	WEAKPUD	XBARE	T1E	T0E	ECIE		PCA0ME[1:0]	
Type	R/W	R/W	R/W	R/W	R/W	R	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xE2

Bit	Name	Function
7	WEAKPUD	**Port I/O Weak Pullup Disable.** 0: Weak Pullups enabled (except for Ports whose I/O are configured for analog mode). 1: Weak Pullups disabled.
6	XBARE	**Crossbar Enable.** 0: Crossbar disabled. 1: Crossbar enabled.
5	T1E	**T1 Enable.** 0: T1 unavailable at Port pin. 1: T1 routed to Port pin.
4	T0E	**T0 Enable.** 0: T0 unavailable at Port pin. 1: T0 routed to Port pin.
3	ECIE	**PCA0 External Counter Input Enable.** 0: ECI unavailable at Port pin. 1: ECI routed to Port pin.
2	Unused	Unused. Read = 0b; Write = Don't Care.
1:0	PCA0ME[1:0]	**PCA Module I/O Enable Bits.** 00: All PCA I/O unavailable at Port pins. 01: CEX0 routed to Port pin. 10: CEX0, CEX1 routed to Port pins. 11: CEX0, CEX1, CEX2 routed to Port pins.

21.5. Special Function Registers for Accessing and Configuring Port I/O

All Port I/O are accessed through corresponding special function registers (SFRs) that are both byte addressable and bit addressable. When writing to a Port, the value written to the SFR is latched to maintain the output data value at each pin. When reading, the logic levels of the Port's input pins are returned regardless of the XBRn settings (i.e., even when the pin is assigned to another signal by the Crossbar, the Port register can always read its corresponding Port I/O pin). The exception to this is the execution of the read-modify-write instructions that target a Port Latch register as the destination. The read-modify-write instructions when operating on a Port SFR are the following: ANL, ORL, XRL, JBC, CPL, INC, DEC, DJNZ and MOV, CLR or SETB, when the destination is an individual bit in a Port SFR. For these instructions, the value of the latch register (not the pin) is read, modified, and written back to the SFR.

Each Port has a corresponding PnSKIP register which allows its individual Port pins to be assigned to digital functions or skipped by the Crossbar. All Port pins used for analog functions, GPIO, or dedicated digital functions such as the EMIF should have their PnSKIP bit set to 1.

The Port input mode of the I/O pins is defined using the Port Input Mode registers (PnMDIN). Each Port cell can be configured for analog or digital I/O. This selection is required even for the digital resources selected in the XBRn registers, and is not automatic.

The output driver characteristics of the I/O pins are defined using the Port Output Mode registers (PnMDOUT). Each Port Output driver can be configured as either open drain or push-pull. This selection is required even for the digital resources selected in the XBRn registers, and is not automatic. The only exception to this is the SMBus (SDA, SCL) pins, which are configured as open-drain regardless of the PnMDOUT settings.

SFR Definition 21.3. P0: Port 0

Bit	7	6	5	4	3	2	1	0
Name	P0[7:0]							
Type	R/W							
Reset	1	1	1	1	1	1	1	1

SFR Address = 0x80; Bit-Addressable

Bit	Name	Description	Write	Read
7:0	P0[7:0]	**Port 0 Data.** Sets the Port latch logic value or reads the Port pin logic state in Port cells configured for digital I/O.	0: Set output latch to logic LOW. 1: Set output latch to logic HIGH.	0: P0.n Port pin is logic LOW. 1: P0.n Port pin is logic HIGH.

26.3.1. Edge-triggered Capture Mode

In this mode, a valid transition on the CEXn pin causes the PCA to capture the value of the PCA counter/timer and load it into the corresponding module's 16-bit capture/compare register (PCA0CPLn and PCA0CPHn). The CAPPn and CAPNn bits in the PCA0CPMn register are used to select the type of transition that triggers the capture: low-to-high transition (positive edge), high-to-low transition (negative edge), or either transition (positive or negative edge). When a capture occurs, the Capture/Compare Flag (CCFn) in PCA0CN is set to logic 1. An interrupt request is generated if the CCFn interrupt for that module is enabled. The CCFn bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software. If both CAPPn and CAPNn bits are set to logic 1, then the state of the Port pin associated with CEXn can be read directly to determine whether a rising-edge or falling-edge caused the capture.

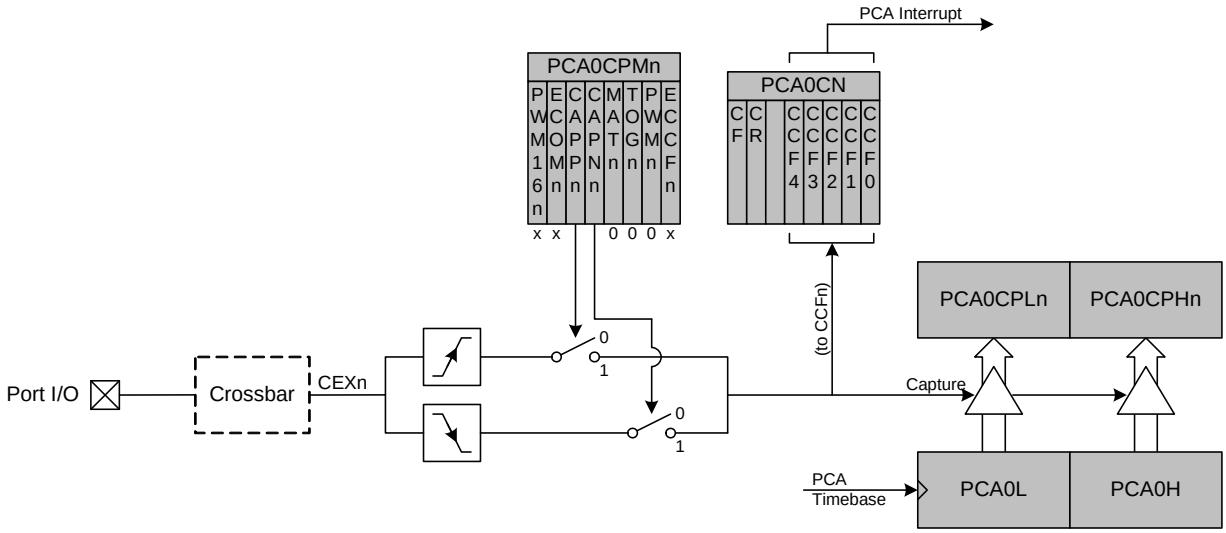


Figure 26.4. PCA Capture Mode Diagram

Note: The CEXn input signal must remain high or low for at least 2 system clock cycles to be recognized by the hardware.

26.3.5. 8-bit Pulse Width Modulator Mode

The duty cycle of the PWM output signal in 8-bit PWM mode is varied using the module's PCA0CPLn capture/compare register. When the value in the low byte of the PCA counter/timer (PCA0L) is equal to the value in PCA0CPLn, the output on the CEXn pin will be set. When the count value in PCA0L overflows, the CEXn output will be reset (see Figure 26.8). Also, when the counter/timer low byte (PCA0L) overflows from 0xFF to 0x00, PCA0CPLn is reloaded automatically with the value stored in the module's capture/compare high byte (PCA0CPHn) without software intervention. Setting the ECOMn and PWMn bits in the PCA0CPMn register enables 8-Bit Pulse Width Modulator mode. If the MATn bit is set to 1, the CCFn flag for the module will be set each time an 8-bit comparator match (rising edge) occurs. The duty cycle for 8-Bit PWM Mode is given in Equation 26.2.

Important Note About Capture/Compare Registers: When writing a 16-bit value to the PCA0 Capture/Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to 0; writing to PCA0CPHn sets ECOMn to 1.

$$\text{Duty Cycle} = \frac{(256 - PCA0CPHn)}{256}$$

Equation 26.2. 8-Bit PWM Duty Cycle

Using Equation 26.2, the largest duty cycle is 100% (PCA0CPHn = 0), and the smallest duty cycle is 0.39% (PCA0CPHn = 0xFF). A 0% duty cycle may be generated by clearing the ECOMn bit to 0.

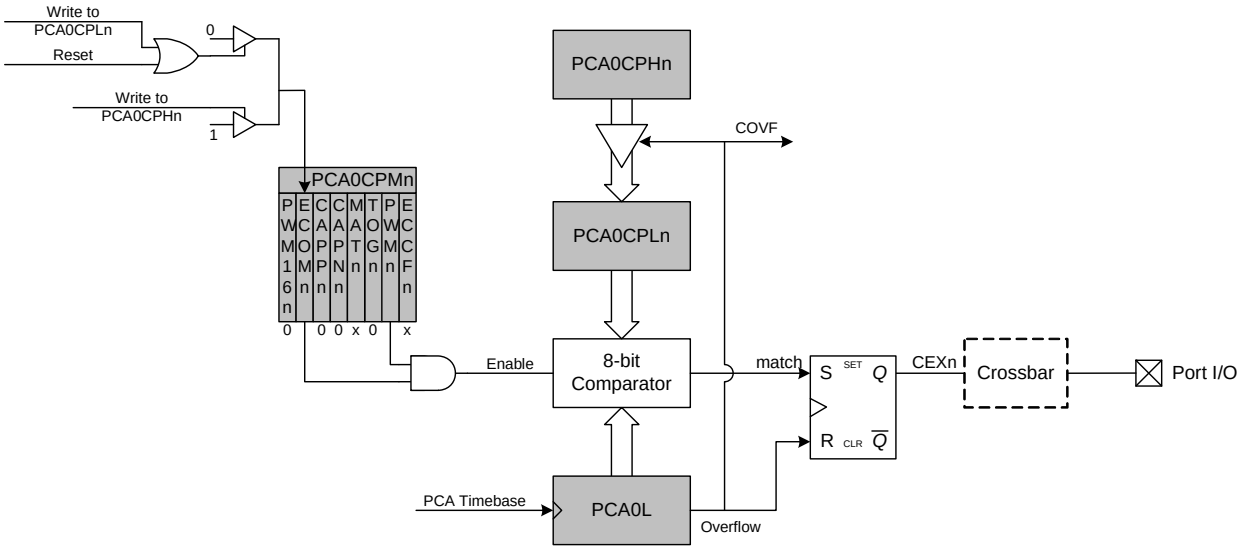


Figure 26.8. PCA 8-Bit PWM Mode Diagram

27.2. C2 Pin Sharing

The C2 protocol allows the C2 pins to be shared with user functions so that in-system debugging and EPROM programming functions may be performed. This is possible because C2 communication is typically performed when the device is in the halt state, where all on-chip peripherals and user software are stalled. In this halted state, the C2 interface can safely “borrow” the C2CK (normally RST) and C2D pins. In most applications, external resistors are required to isolate C2 interface traffic from the user application when performing debug functions. These external resistors are not necessary for production boards. A typical isolation configuration is shown in Figure 27.1.

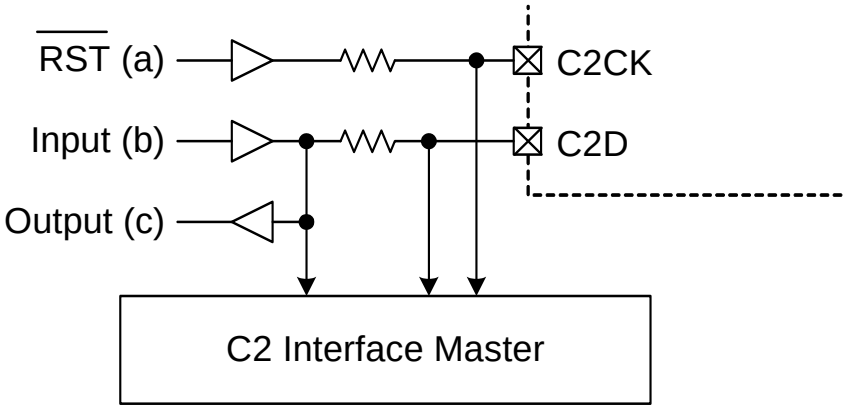


Figure 27.1. Typical C2 Pin Sharing

The configuration in Figure 27.1 assumes the following:

1. The user input (b) cannot change state while the target device is halted.
2. The $\overline{\text{RST}}$ pin on the target device is used as an input only.

Additional resistors may be necessary depending on the specific application.